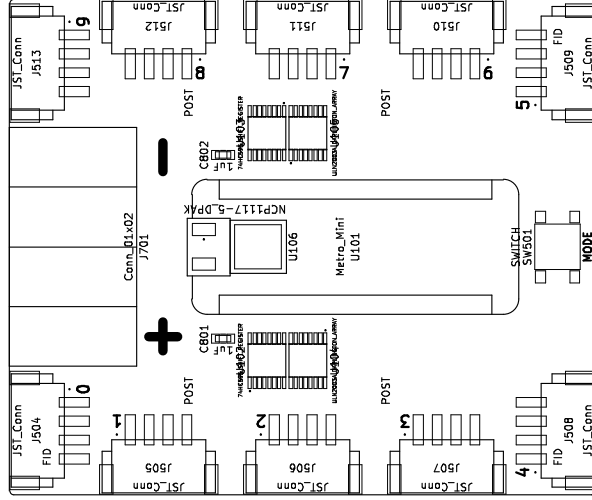


Fabrication Notes:
1) Fabricate to meet or exceed IPC 6011/6012 Class 2, as defined in IPC 2221

- 1) Fabricate to meet or exceed IPC 6011/6012 Class 2, as defined in IPC 2221
- 2) Substrate for core and prepreg is FR-4 TG130
- 3) Board finish is HASL Lead Free
- 4) Materials to meet UL 94 V-0 flammability specification
- 5) Minimum trace width 6 mil, minimum spacing 6 mil
- 6) Apply LPI soldermask (black) on front and back side
- 7) Silkscreen on top and bottom side using (white) epoxy ink
- 8) All dimensions and hole sizes in mm except where noted
- 9) IF IN DOUBT – ASK

Layer Stackup

Layer:	Material:	Thickness:	Tolerance:
Top Paste	Pb-Free		
Top Overlay	Epoxy Ink		
Top Solder	Solder Resist	1mil	+/- 0.2mil
Top Layer	10z. Copper	1.35mil	+/- 0.135mil
Dielectric 1	FR-4 TG130	60mil	+/- 6mil
Bottom Layer	10z. Copper	1.35mil	+/- 0.135mil
Bottom Solder	Solder Resist	1mil	+/- 0.2mil
Bottom Overlay	Epoxy Ink		
Bottom Paste	Pb-Free		



IF IN DOUBT - ASK

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Sheet:
File: Console_Lights.kicad_pcb

Title: Console Lights Layout

Size: A	Date: 2018-12-14
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<p> KiCad E.D.A. kiCad 4.0.7-e2-637658ubuntu16.04.1 </p>	<p> DATE: 2018-11-12 </p>
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Rev: 0.1

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